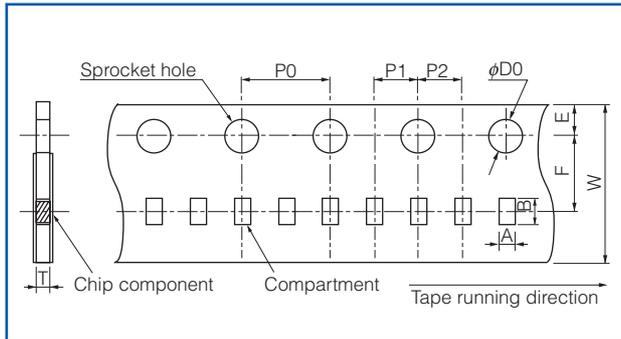


Packaging Methods (Taping)

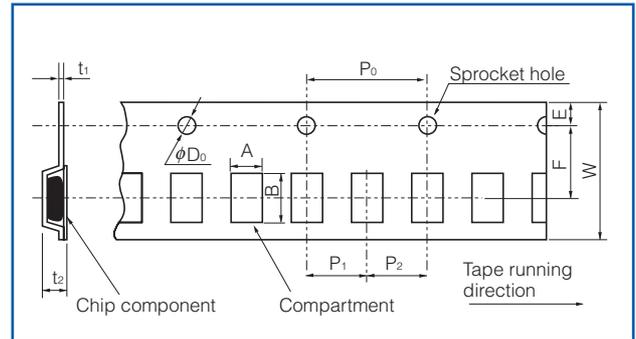
● Standard Quantity

Part Number	Size (inch)	Type	Kind of Taping	Pitch (P ₁)	Quantity
EXCX4C	0202	Single	Pressed Carrier Taping	2 mm	10,000 pcs./reel
EXC14C	0302			2 mm	10,000 pcs./reel
EXC24C	0504				
EXC34C	0805	Array	Embossed Carrier Taping	4 mm	5,000 pcs./reel
EXC18C	0603				
EXC28C	0804				

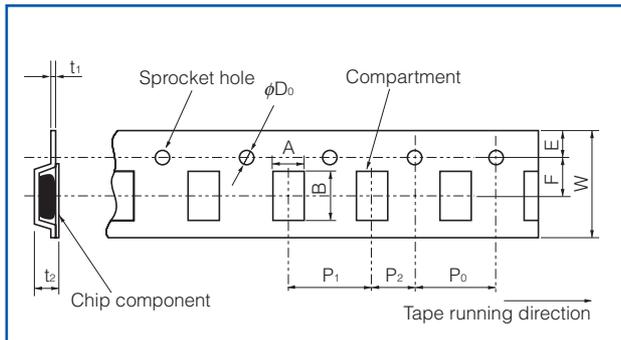
● Pressed Carrier Taping EXCX4C



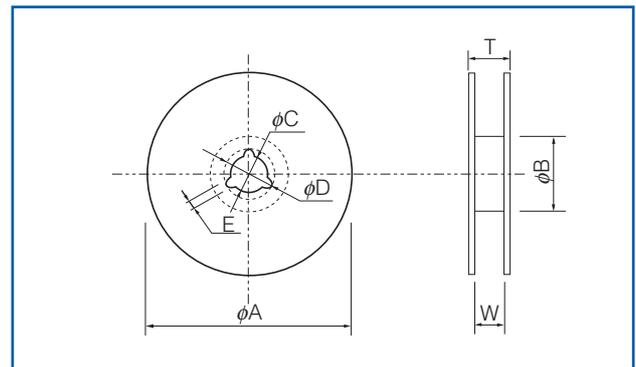
● Embossed Carrier Taping EXC14C



● Embossed Carrier Taping EXC18C, 24C, 28C, 34C



● Taping Reel



● Pressed Carrier Taping

(mm)

Part Number	A	B	W	F	E	P ₁	P ₂	P ₀	φD ₀	T
EXCX4C	0.60±0.10	0.80±0.10	8.0±0.2	3.50±0.05	1.75±0.10	2.0±0.1	2.0±0.1	4.0±0.1	1.5 ^{+0.1} ₀	0.35 typ.

● Embossed Carrier Taping

(mm)

Part Number	A	B	W	F	E	P ₁	P ₂	P ₀	φD ₀	t ₁	t ₂
EXC14C	0.75±0.10	0.95±0.10	8.0±0.2	3.50±0.05	1.75±0.10	2.0±0.1	2.0±0.1	4.0±0.1	1.5 ^{+0.1} ₀	0.25±0.05	0.85±0.15
EXC18C	1.00±0.10	1.80±0.10									0.80±0.05
EXC24C	1.20±0.15	1.45±0.15									0.90±0.15
EXC28C		2.25±0.15									
EXC34C	1.50±0.20	2.30±0.20									

● Taping Reel

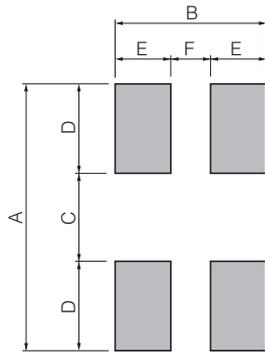
Standard Reel Dimensions

(mm)

Part Number	φA	φB	φC	φD	E	W	T
EXCX4C	180.0±3.0	60.0±1.0	13.0±0.2	21.0±0.8	2.0±0.5	9.0±0.3	11.4±1.0
EXC14C			13.0±0.5				11.4±1.5
EXC18C							
EXC24C							
EXC28C							
EXC34C							

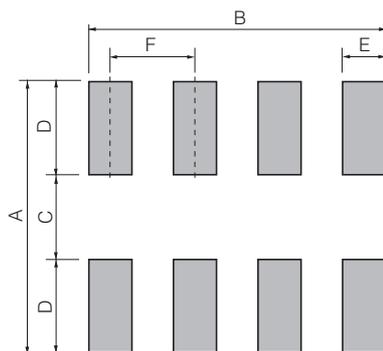
Recommended Land Pattern Design

● Single



Part Number	Dimensions (mm)					
	A	B	C	D	E	F
EXCX4C	0.80 to 0.90	0.60 to 0.75	0.20 to 0.30	0.30	0.20 to 0.25	0.20 to 0.25
EXC14C	0.80 to 1.00	0.80	0.30	0.25 to 0.35	0.30	0.20
EXC24C	1.60 to 2.00	0.95	0.70	0.45 to 0.65	0.35	0.25
EXC34C	2.60	1.20	1.10	0.75	0.40	0.40

● Array



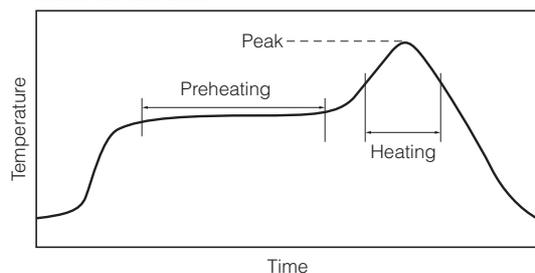
Part Number	Dimensions (mm)					
	A	B	C	D	E	F
EXC18C	1.4	1.4	0.4	0.5	0.2	0.4
EXC28C	1.4	1.75	0.4	0.5	0.25	0.5

Recommended Soldering Conditions

Recommendations and precautions are described below

● Recommended soldering conditions for reflow

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



● Flow soldering

- We do not recommend flow soldering, because flow soldering may cause bridges between the electrodes.

For soldering (Example : Sn-37Pb)

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 10 °C	max. 10 s

For lead-free soldering (Example : Sn/3Ag/0.5Cu)

	Temperature	Time
Preheating	150 °C to 170 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

<Repair with hand soldering>

- Preheat with a blast of hot air or similar method. Use a soldering iron with a tip temperature of 350 °C or less. Solder each electrode for 3 seconds or less.
- Never touch this product with the tip of a soldering iron.

⚠ Safety Precautions

The following are precautions for individual products. Please also refer to the common precautions for EMC Components in this catalog.

1. Use rosin-based flux or halogen-free flux.
2. For cleaning, use an alcohol-based cleaning agent. Before using any other type, consult with our sales person in advance.
3. Do not apply shock to Common mode Noise Filters (hereafter called the filters) or pinch them with a hard tool (e.g. pliers and tweezers). Otherwise, their bodies may be chipped, affecting their performance. Excessive mechanical stress may damage the filters. Handle with care.
4. Store the filters in a location with a temperature ranging from -5 °C to +40 °C and a relative humidity of 40 % to 60 % , where there are no rapid changes in temperature or humidity.
5. Use the filters within a year after the date of the outgoing inspection indicated on the packages.